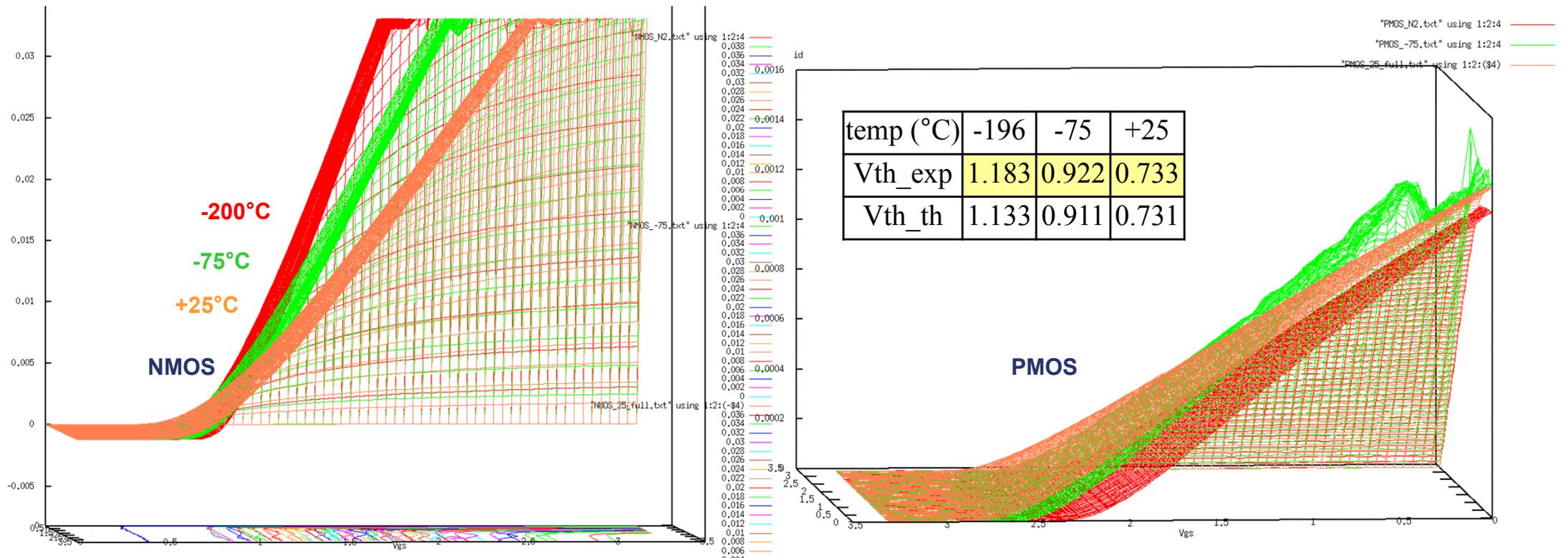


Front-end a basse (cryogenic) temperature

- MOS
- Resistance
- Capa...
- Delai inverseur
- 1/f noise
- Setup instrum
- Tips and traps
- Composants discrets

MOS

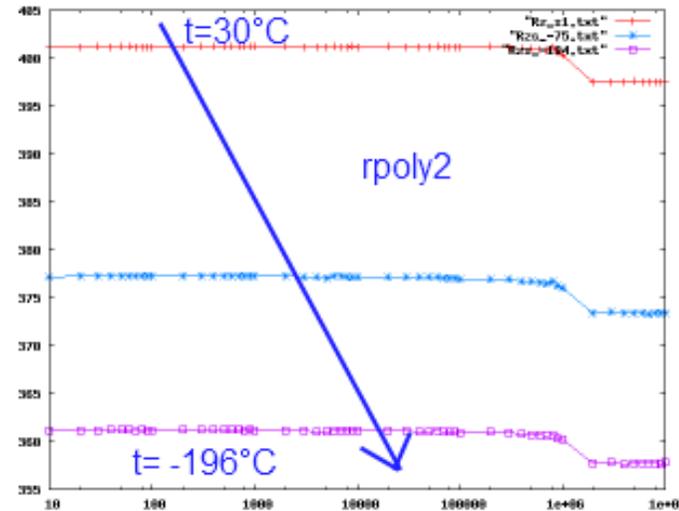
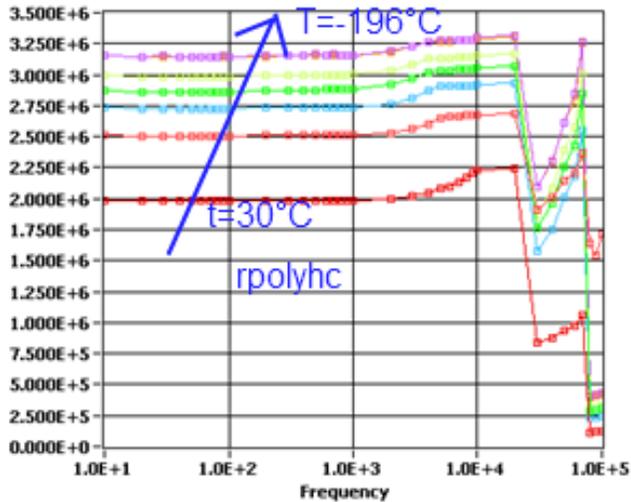
- $T \downarrow$, la mobilité μ augmente $\rightarrow gm \propto \mu C_{ox}$ augmente
- $T \downarrow$, V_{th} \uparrow



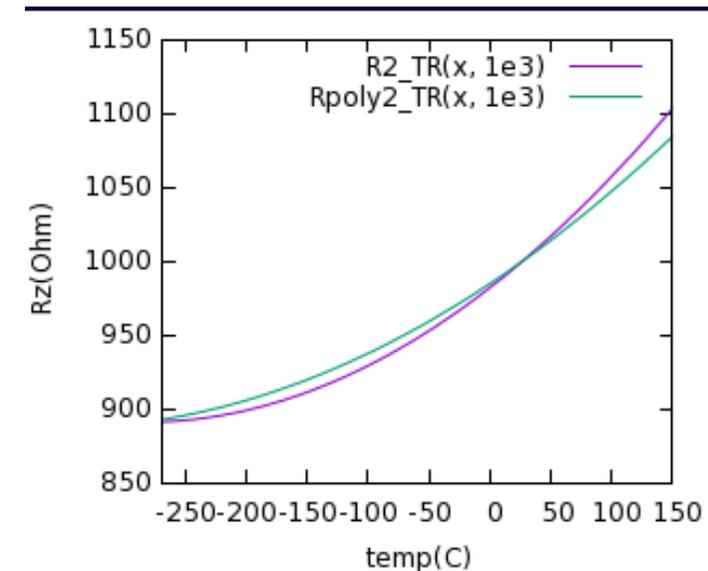
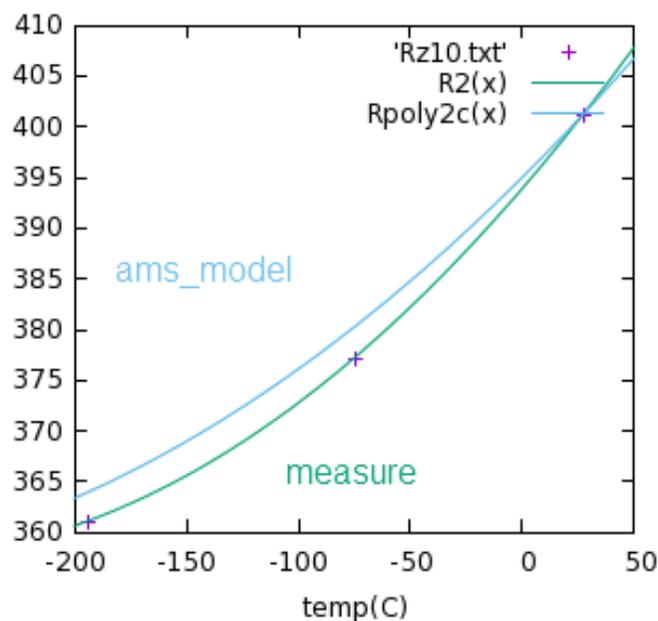
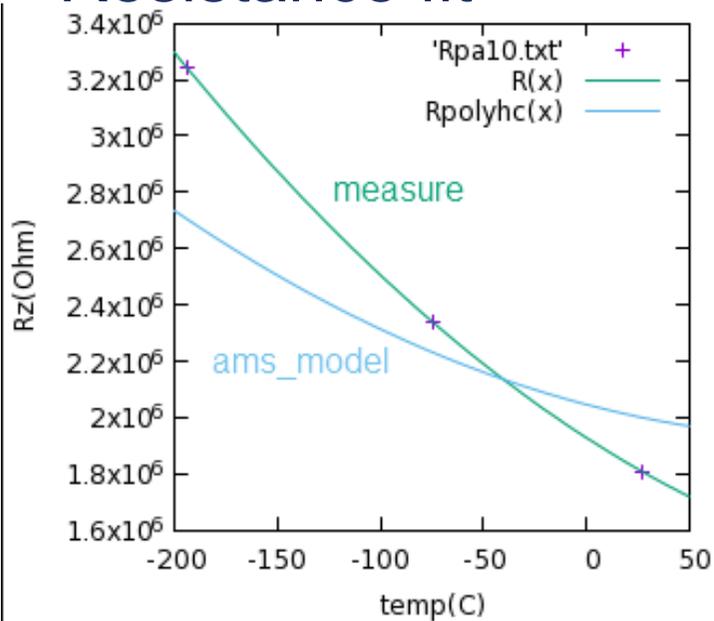
Resistance

$$R(T) = R(T0) \cdot (1 + TCR1(T - T0) + TCR2(T - T0)^2)$$

T0	RT0		TCR1 (10 ⁻³ Ω/K)		TCR2 (10 ⁻⁶ Ω/K)	
	spec.	exp	spec.	exp	spec.	Exp
rpoly2	350Ω	360Ω	0.59	0.70	7.7	1.17
rpolyhc	2MΩ	1.8MΩ	-0.75	-2.37	3.82	5.70

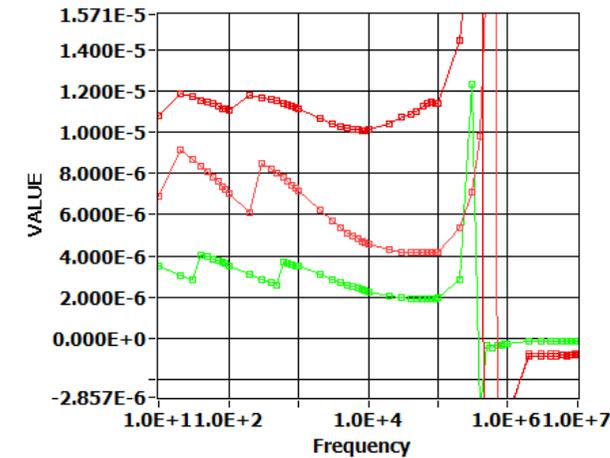
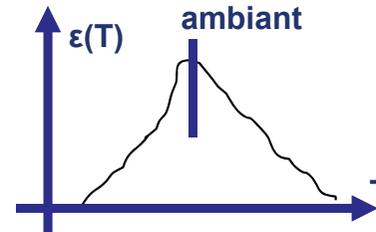


Resistance fit



Capa...

- CMS : COG/NPO => valeur max (de taille :1210) → 100nF
- Tantale : à éviter, PB de vieillissement
- Capa CMS X5R X7R, YUV ...
 - quand t°C diminue C diminue,
- Capa intégré [OK]
- Danger techno 'high kè' $K = \epsilon(T) / \epsilon_0$
 - Modif de la capa à froid → vth ↗

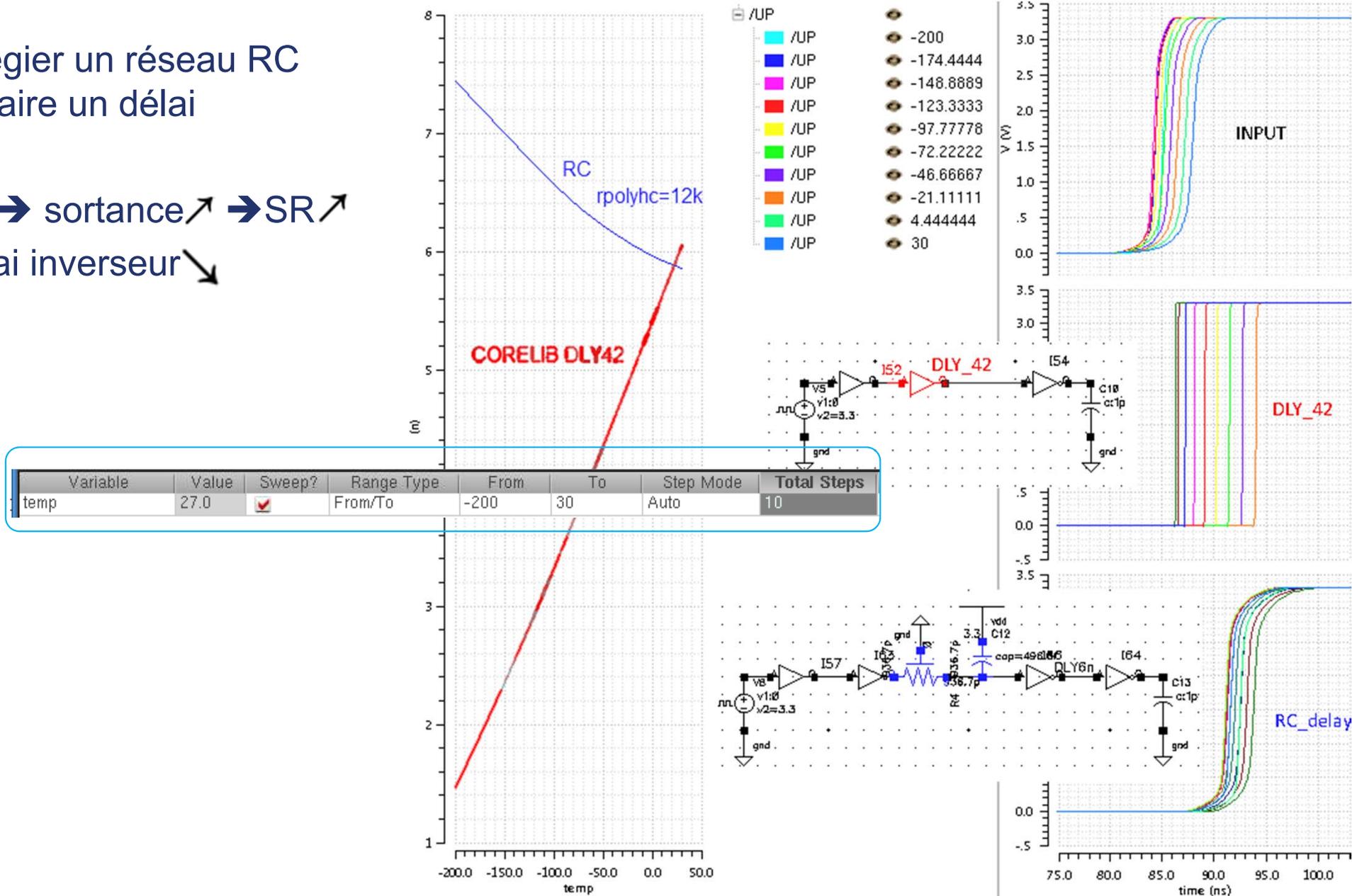


Capacitor type	Measured capacitance (100 nF at 300 K)		f \ T	Measured ESR		
	77 K	4 K		300 K	77 K	4 K
X7R ceramic	21.3 nF	3.4 nF	1 kHz	76 Ω	574 Ω	5.6 MΩ
			10 kHz	1.5 Ω	64 Ω	400 kΩ
			100 kHz	0.3 Ω	7.6 Ω	62 kΩ
Y5V ceramic	1.8 nF	0.9 nF	1 kHz	93 Ω	3940 Ω	3910 Ω
			10 kHz	1.8 Ω	410 Ω	360 Ω
			100 kHz	0.6 Ω	50 Ω	40 Ω
NPO ceramic (NPO/COG/COH)	100.2 nF	99.7 nF	1 kHz	2.1 Ω	2 Ω	3 Ω
			10 kHz	0.3 Ω	0.4 Ω	0.1 Ω
			100 kHz	0.2 Ω	0.02 Ω	0.05 Ω
Polyester	71.8 nF	15.3 nF	1 kHz	42 Ω	37 Ω	340 Ω
			10 kHz	1.8 Ω	40 Ω	36 Ω
			100 kHz	0.8 Ω	19 Ω	18 Ω
PPS	92 nF	83.2 nF	1 kHz	21 Ω	4.4 Ω	3.1 Ω
			10 kHz	1.1 Ω	0.2 Ω	0.25 Ω
			100 kHz	0.2 Ω	0.02 Ω	0.3 Ω

<http://hal-obspm.ccsd.cnrs.fr/hal-00623399/document>

Privilégier un réseau RC pour faire un délai

gm ↗ → sortance ↗ → SR ↗
 → délai inverseur ↘



delai ~constant de -200°C à 30°C

- En jouant sur les variations inverse de r_{poly2} et r_{polyh} en température

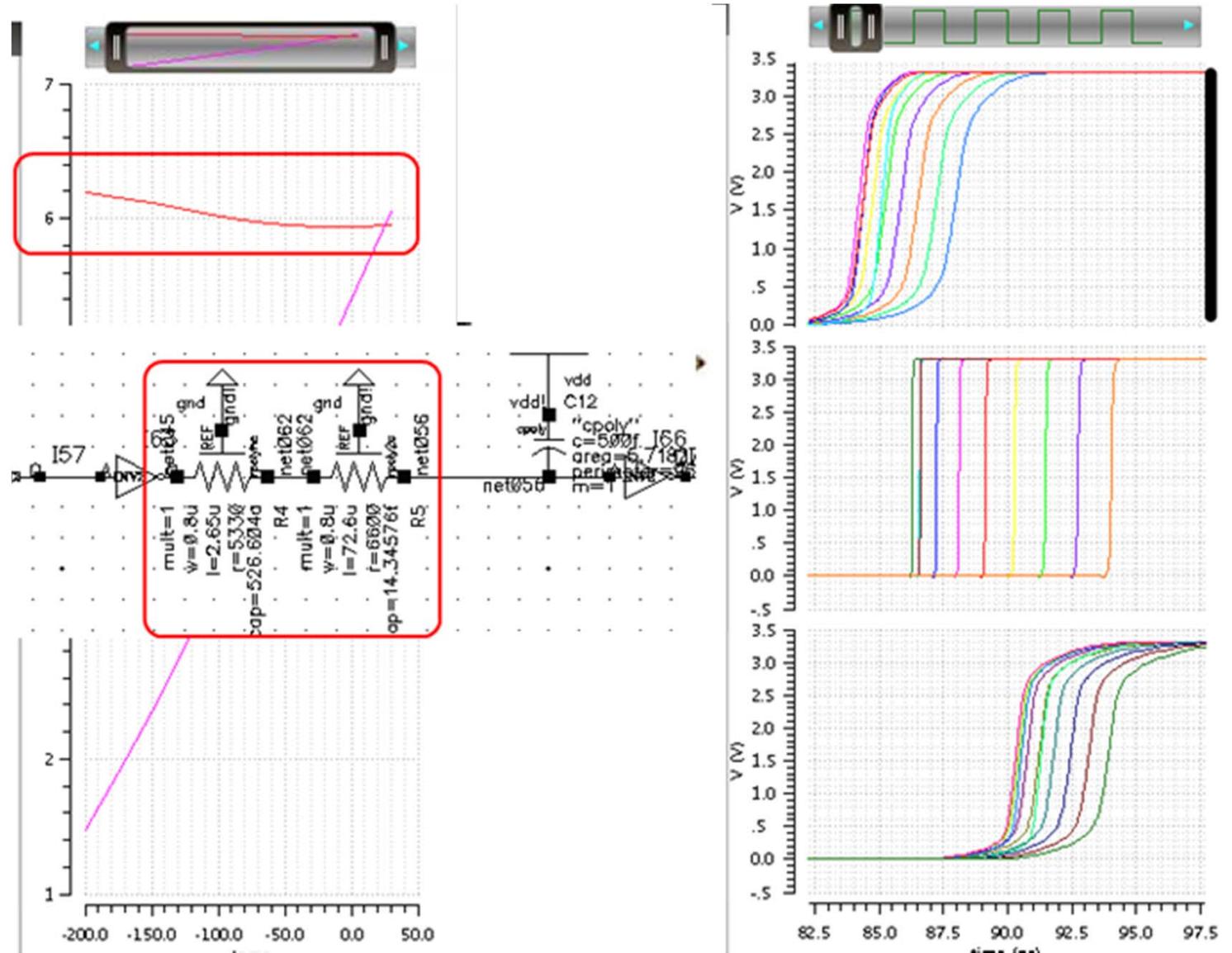
Au premier ordre pour conserver R_{total} constant :

$$R_{polyh} = R_{poly2} \cdot 0.59 / 0.75$$

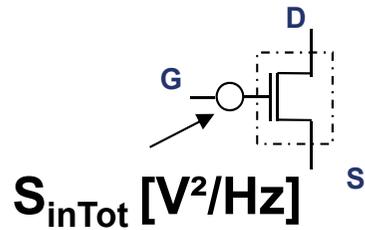
$$R_{tot} = 12k = 5.33k + 6.6k$$

$$\rightarrow \tau = 1/2/3.14 / (12k \cdot 500f) = 6ns$$

~constante sur [-200°C +30°C]



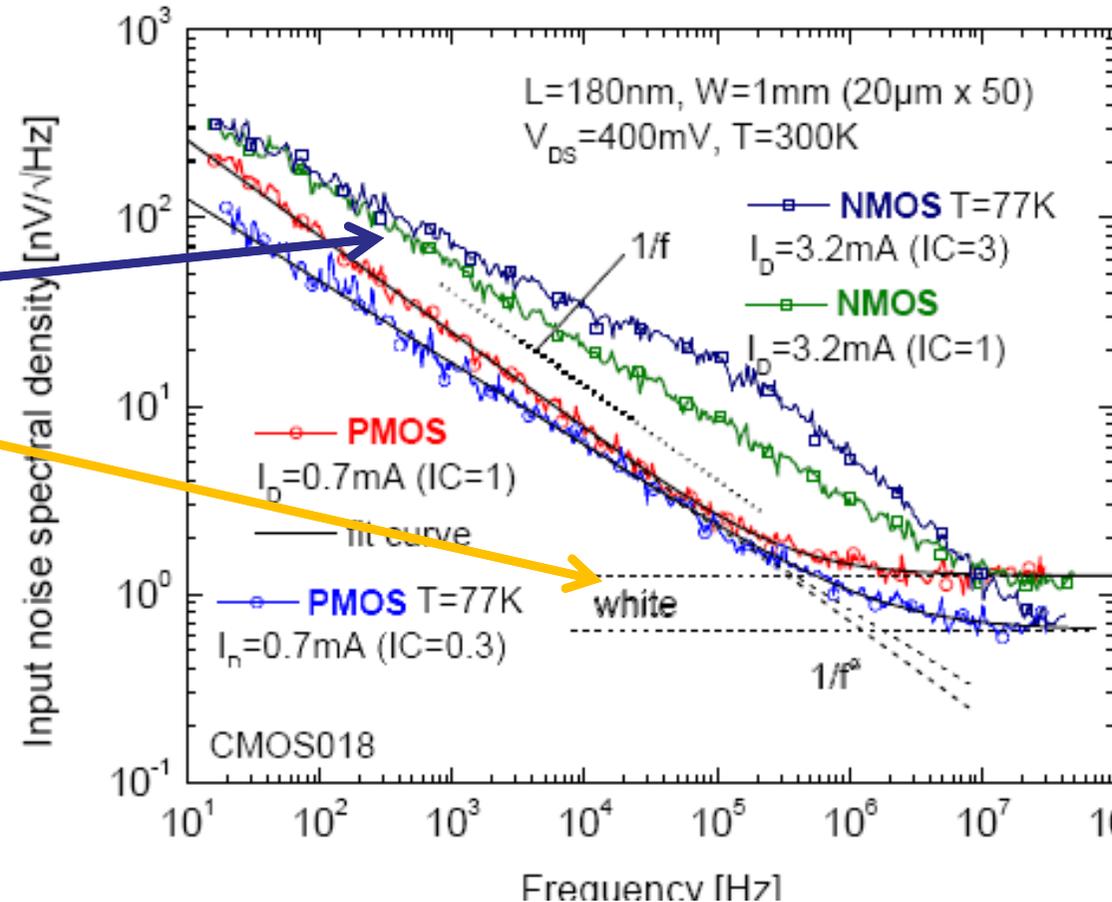
1/f noise



$$S_{inTot} = 4kTR_N$$

$$R_N = \frac{\rho}{WLf} + \frac{n}{g_m}$$

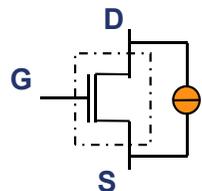
- Nécessité de contraindre le simulateur pour prévoir des pentes de bruit en 1/f plus contraignantes.
- Sinon, les résultats sont éloignés des prédictions...



Radeka, De Geronimo NSS2010

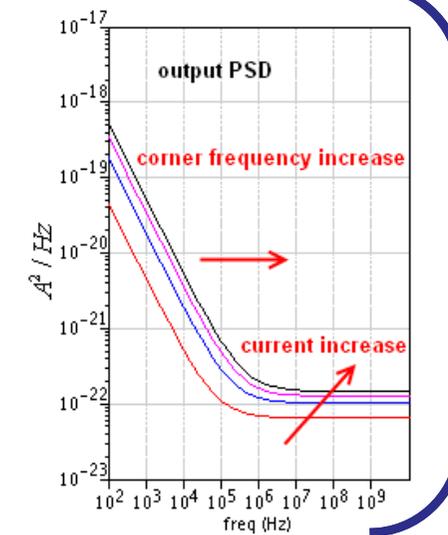
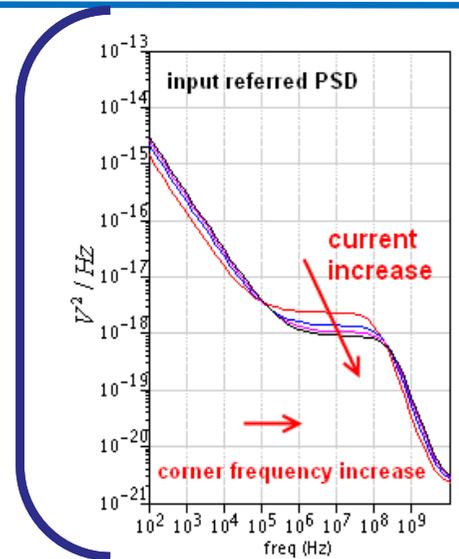
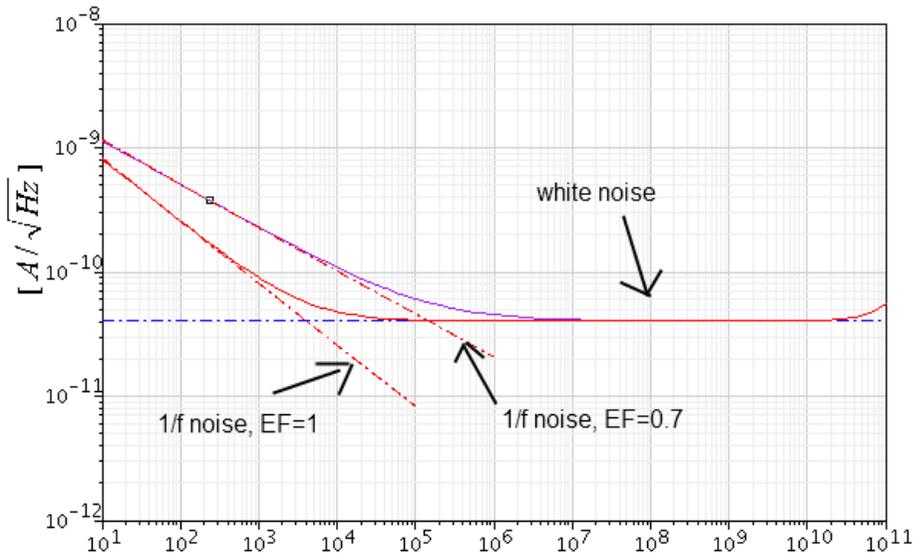
➔ Augmenter L : la largeur des transistors à W/L constant ➔ augmentation de la surface

$$S_{lf} = \frac{K_f \cdot I_d^{AF}}{C_{ox} \cdot WL \cdot f^{EF}} \quad [A^2/Hz] \quad S_{th} = \frac{2}{3} 4kTg_m \quad [A^2/Hz]$$



Output referred noise

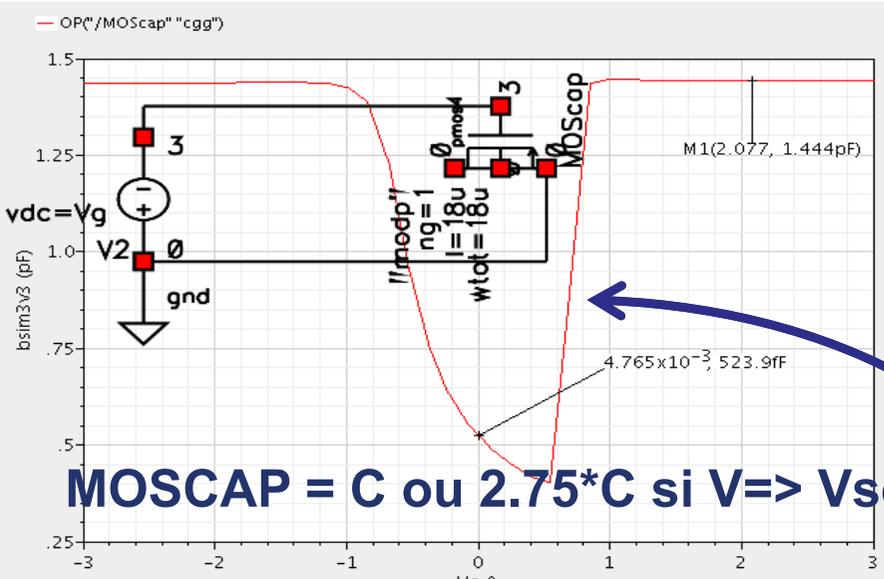
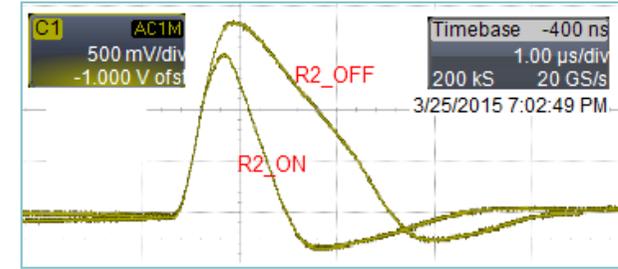
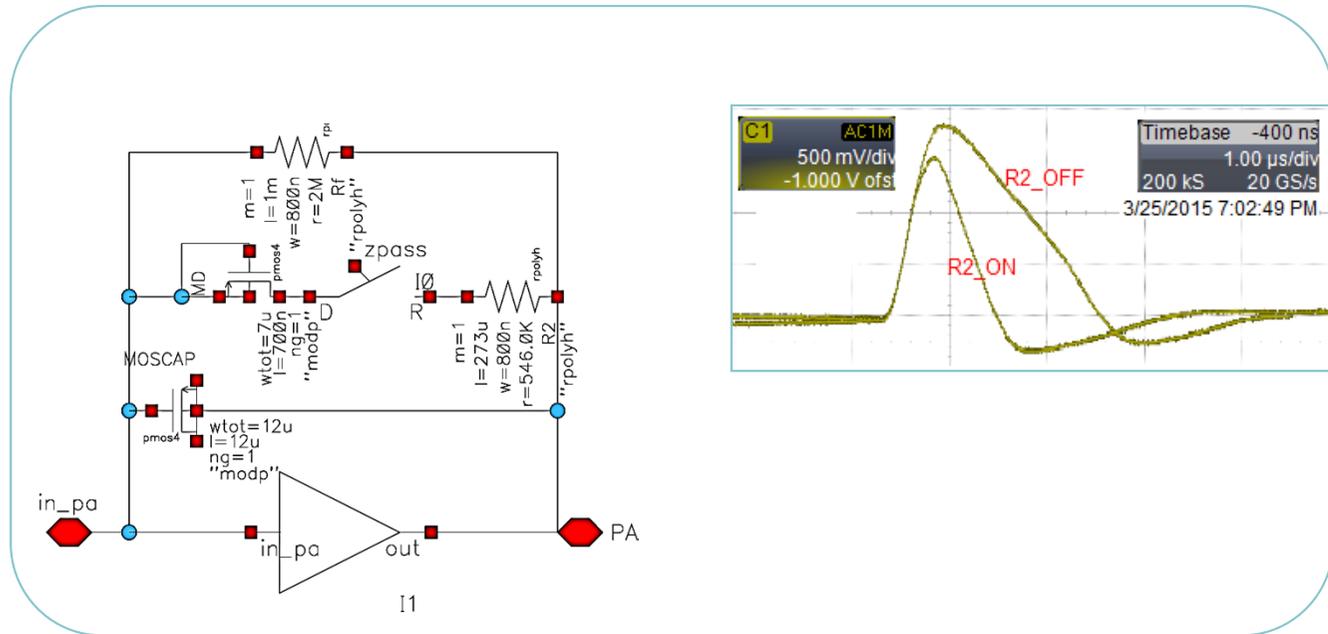
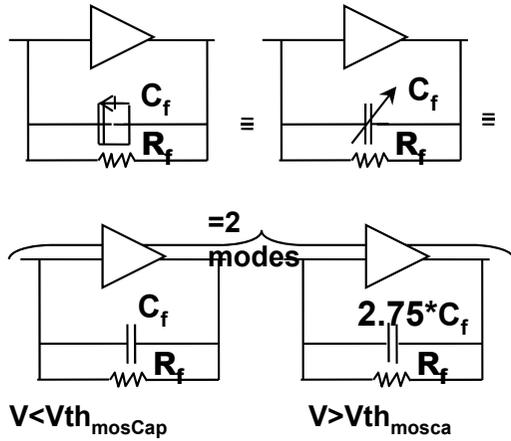
$S_{outTot} [A^2/Hz]$



$$S_{outTot} [A^2/Hz] = g_m^2 \cdot S_{inTot} [V^2/Hz]$$

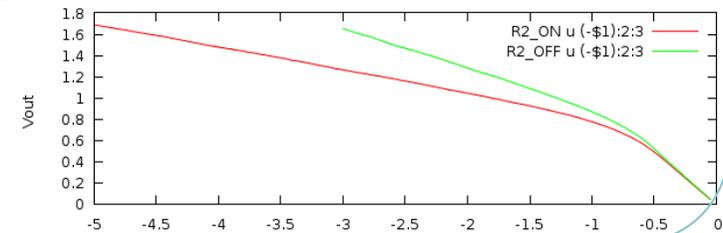
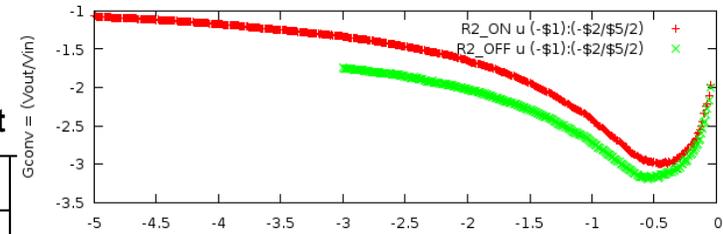
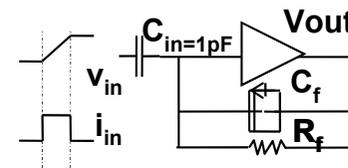
temp	↘	↘
gm	↗	↗
	$f_{con}^{IN} = \left(\frac{K_f \cdot I_d^{AF} \cdot g_m}{C_{ox} \cdot WL \cdot \frac{2}{3} 4kT} \right)^{\frac{1}{EF}}$	$f_{con}^{OUT} = \left(\frac{K_f \cdot I_d^{AF}}{C_{ox} \cdot WL \cdot \frac{2}{3} 4kT g_m} \right)^{\frac{1}{EF}}$
	↗	↘

LARZIC_2014

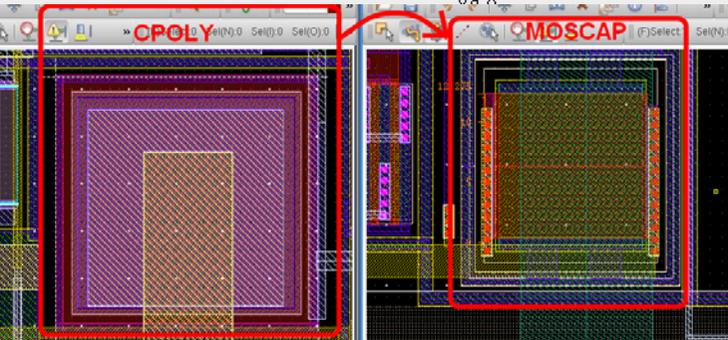


MOSCAP = C ou 2.75*C si V=> Vseuil

**Gconv={2.5 ..1.5}[V/V] à travers 1pF
={2.5 ..1.5}[mV/fC]**



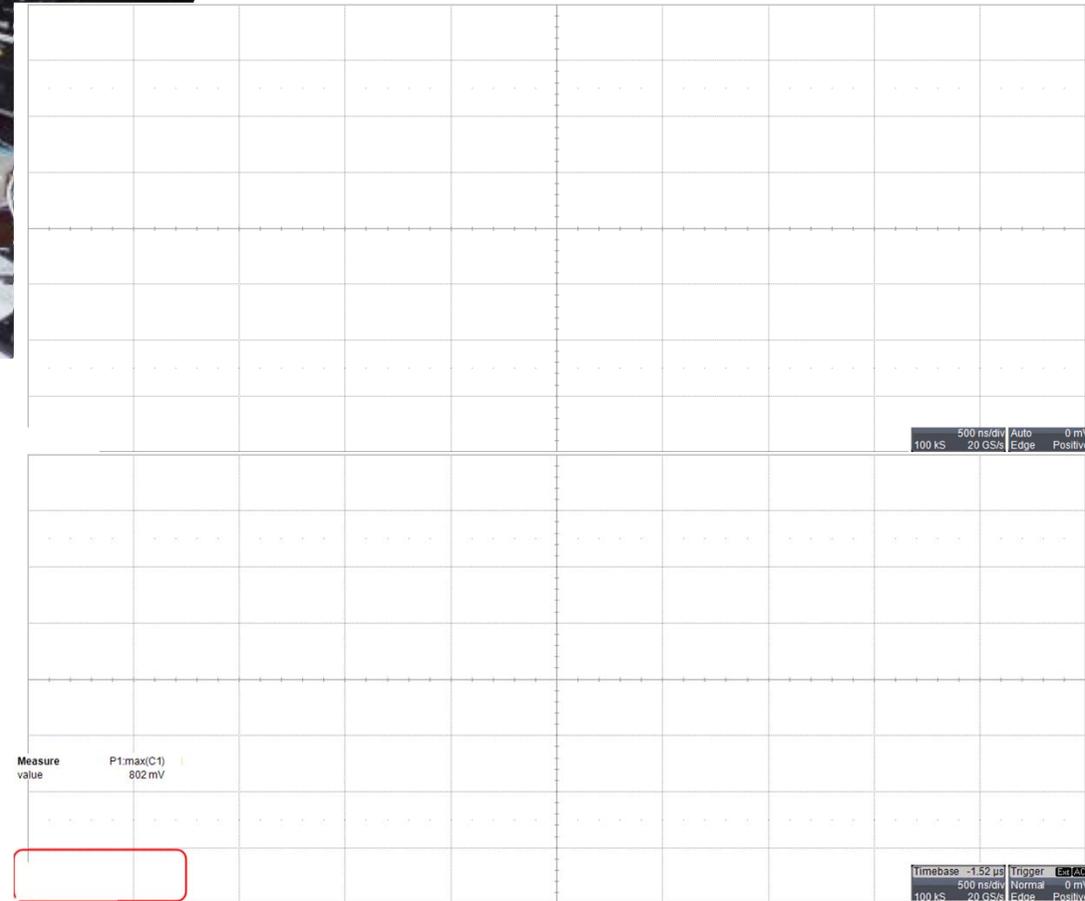
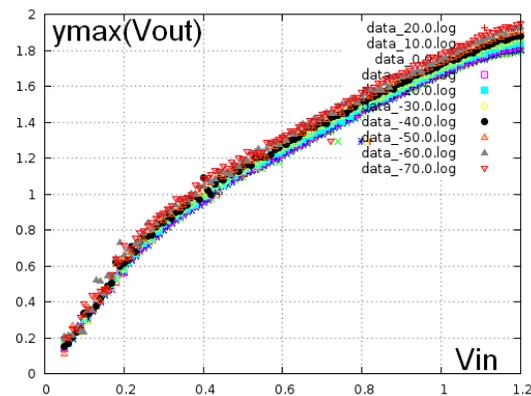
**Sens de la MOSCAP
choisit pour avoir la
transition la plus
franche**

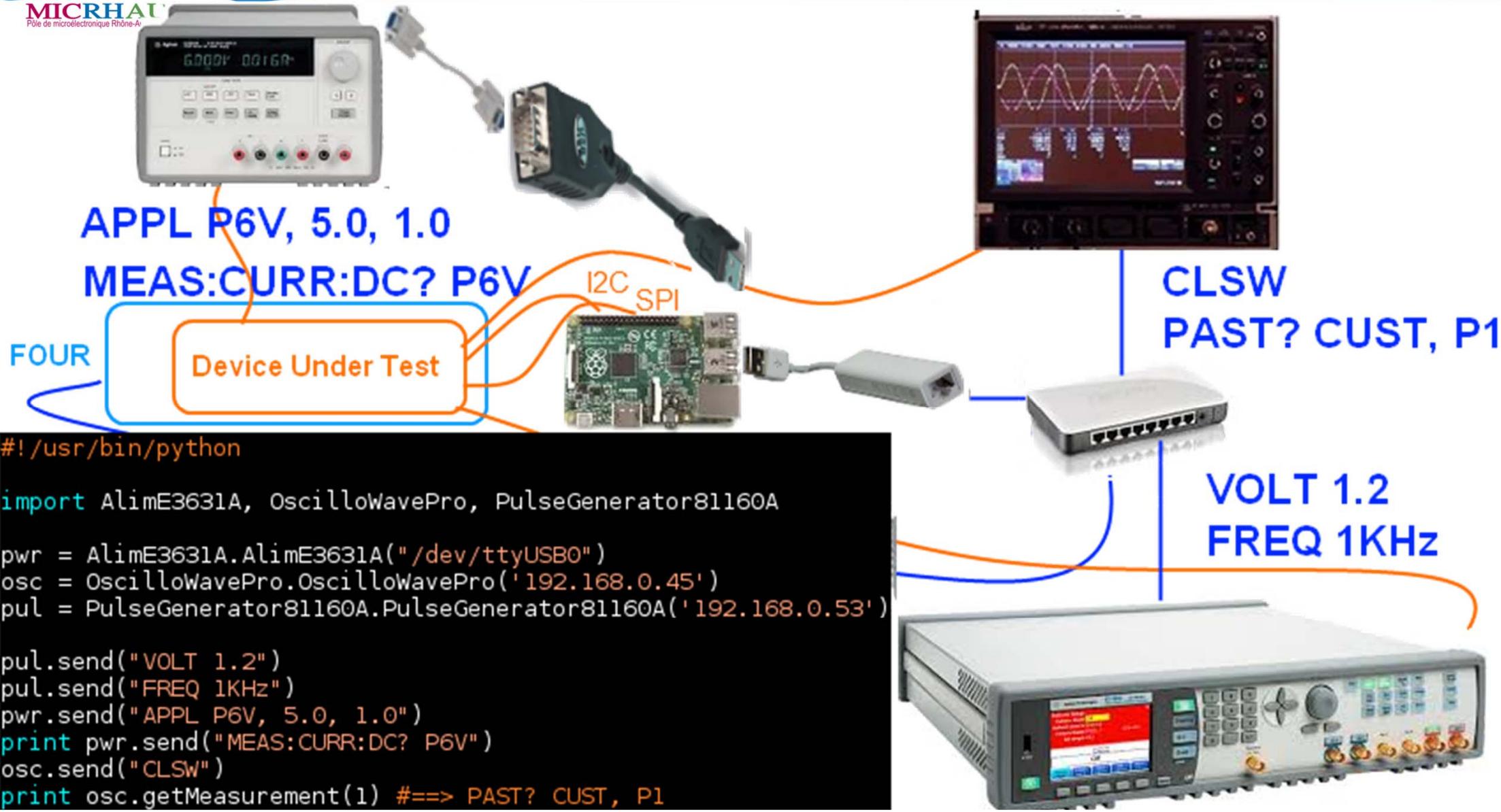


Setup instrum'



- BOM :
four (-70°C +180°C) , géné, Alim, ohmMetre (pt100), rpi...
- LN2 à l'air libre → pas d'obligation de cryostat fermé
- TODO : circulation LN2 pour test asservit de -200°C - 70°C dans four asséché





Merci beaucoup à Loup BALLEYGUIER pour son aide sur les drivers, (CDD→juin 2015)
 → <https://github.com/ebecheto/testbench>

Composants discrets

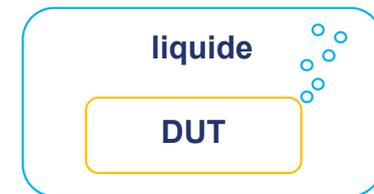
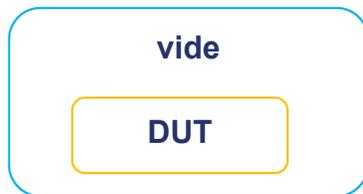
- GPIO expander [OK] , testé dans LN2 : NXP, Ti
- LDO [OK], mais PSRR diminue, testé : TPS73233
 - Paper : *Evaluation of Voltage Reference Circuits and N-Channel Field Effect Transistors at Low Temperatures*,
Richard.L.Patterson@grc.nasa.gov
- dream_twepp2014.pdf → régulateur intégré !
- DC/DC ? [non testé]
- Relai, Moteur [pass/fail]



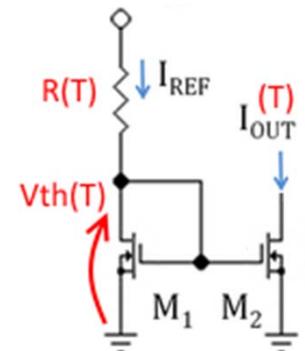
Tips and traps

- Eviter les connecteurs à ressort (JLCC) → souder les ASIC et les connecteurs
- Si condensation lors d'un réchauffement → eau possible sous les composants

/!\ auto-échauffement | conduct. therm. LN2 : $24\text{mW}/\text{m}^{-1}\text{K}^{-1}$ |



- Préférer un Bandgap à un miroir de courant simple
- PSRR → circuits différentiels



- Bsim Models : Res, cap, Vth [OK]
- /\ power supply /\
- Digital design should work.
- 1/f noise ...
- Il existe actionneur → moteur